# 2SC2778

## Silicon NPN epitaxial planar type

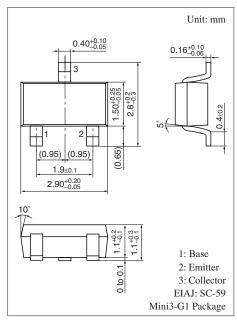
### For high-frequency amplification

#### ■ Features

- Optimum for RF amplification, oscillation, mixing, and IF of FM/AM radios
- Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	30	V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	20	V
Emitter-base voltage (Collector open)	$V_{EBO}$	5	V
Collector current	$I_{C}$	30	mA
Collector power dissipation	P <sub>C</sub>	200	mW
Junction temperature	T <sub>j</sub>	150	°C
Storage temperature	$T_{stg}$	-55 to +150	°C



Marking Symbol: K

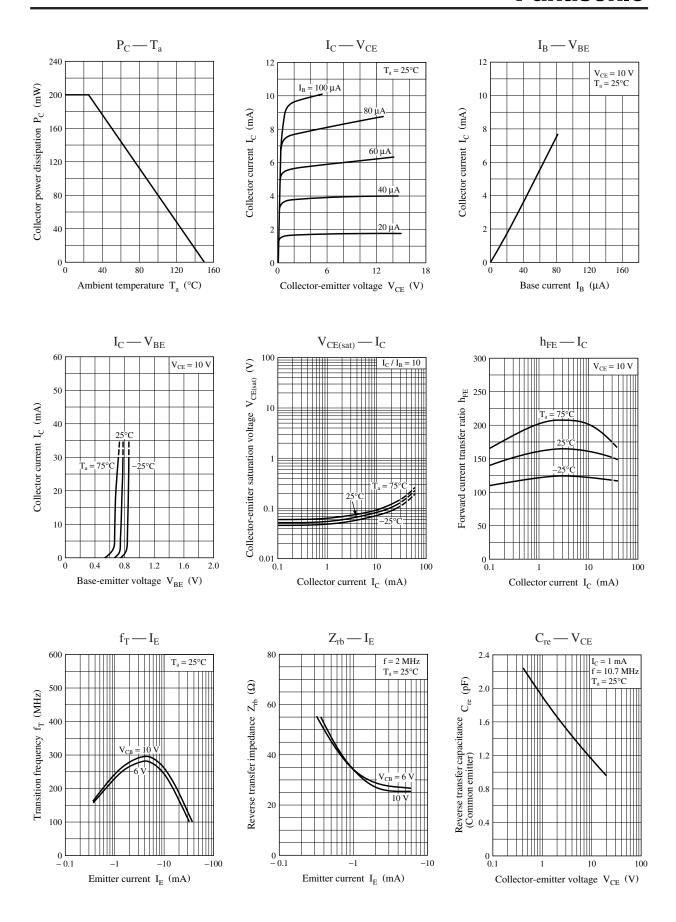
## ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_C = 10 \ \mu A, I_E = 0$	30			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = 2 \text{ mA}, I_B = 0$	20			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = 10 \ \mu A, \ I_C = 0$	5			V
Forward current transfer ratio *	h <sub>FE</sub>	$V_{CE} = 10 \text{ V}, I_{C} = 1 \text{ mA}$	70		250	_
Transition frequency	$f_T$	$V_{CB} = 10 \text{ V}, I_E = -1 \text{ mA}, f = 200 \text{ MHz}$	150	230		MHz
Reverse transfer capacitance	C <sub>re</sub>	$V_{CB} = 10 \text{ V}, I_{E} = -1 \text{ mA}, f = 10.7 \text{ MHz}$		1.3		pF
(Common emitter)						

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

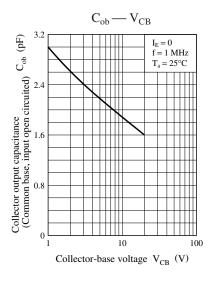
#### 2. \*: Rank classification

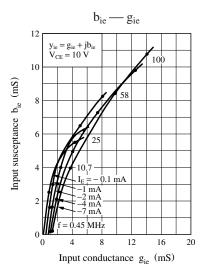
Rank	В	С
$h_{\mathrm{FE}}$	70 to 160	110 to 250

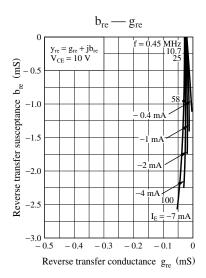


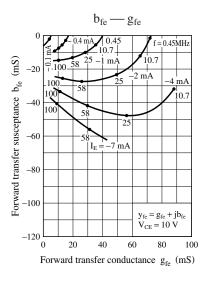
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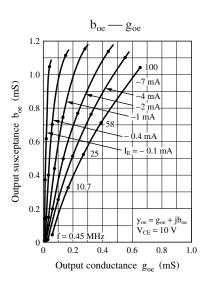
## **Panasonic**











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